

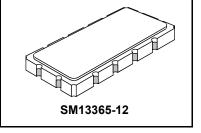


#### • Precision IF SAW Filter

- Hermetic 13.3 x 6.5 mm Surface-mount Case
- Complies with Directive 2002/95/EC (RoHS)
- Moisture Sensitivity Level: 1

# 140 MHz SAW Filter

SF2189A



#### **Absolute Maximum Ratings**

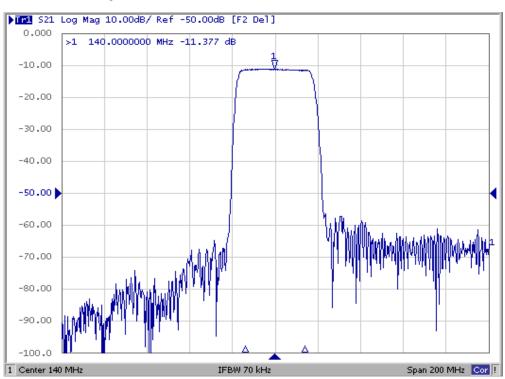
Rating	Value	Units	
Maximum Incident Power in Passband	+10	dBm	
Maximum DC Voltage between any Two Terminals	3	VDC	
Storage Temperature Range in Tape and Reel	-40 to +85 °C		
Suitable for Lead-free Soldering - Maximum Soldering Profile	260°C for 30 s		

#### **Electrical Characteristics**

Characteristic	Sym	Notes	Min	Тур	Max	Units
Center Frequency	F <sub>C</sub>			140		MHz
Minimum Insertion Loss	IL <sub>MIN</sub>			11.3	13.0	dB
1 dB Bandwidth	BW <sub>1</sub>		30.0	33.0		MHz
3 dB Bandwidth	BW <sub>3</sub>		32.0	35.0		MHz
35 dB Bandwidth	BW <sub>35</sub>			42.4	44.0	MHz
Passband Amplitude Ripple, 80% of 3 dB Bandwidth				0.6	1.2	dB <sub>P-P</sub>
Passband Group Delay Ripple, 80% of 3 dB Bandwidth				50	120	ns <sub>P-P</sub>
Passband Absolute Group Delay				0.55		μs
Passband Phase Linearity, 80% of 3 dB Bandwidth				5	14	deg <sub>P-P</sub>
Specification Temperature Range			-20		+80	°C
Operable Temperature Range			-45		+125	°C
Frequency Temperature Coefficient				-94		ppm/°C
Source Impedance				50		ohm
Load Impedance				50		ohm
Case Style		SM133	365-12 13.3 x	6.5 mm Nomin	al Footprint	
Lid Symbolization (YY = year, WW = week, S = Shift, ## = Sequence Code)		SF2189A <u>YYWWS##</u>				

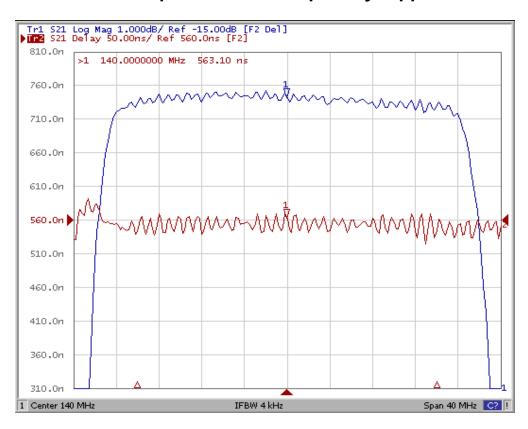
## CAUTION: Electrostatic Sensitive Device. Observe precautions for handling.

- 1. The design, manufacturing process, and specifications of this device are subject to change.
- 2. US or International patents may apply.
- 3. RoHS compliant from the first date of manufacture.

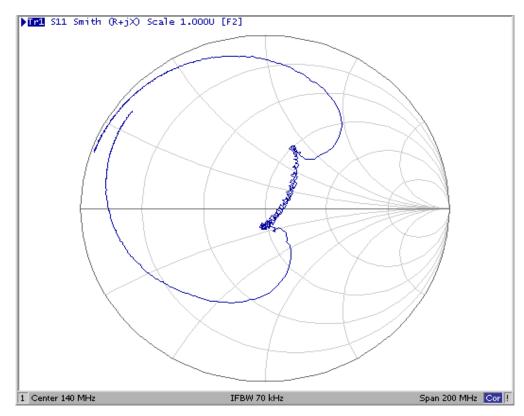


### SF2189A Filter Response

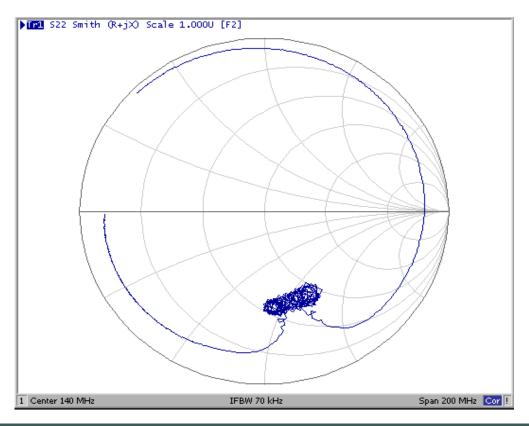
#### SF2189A Passband Amplitude and Group Delay Ripple



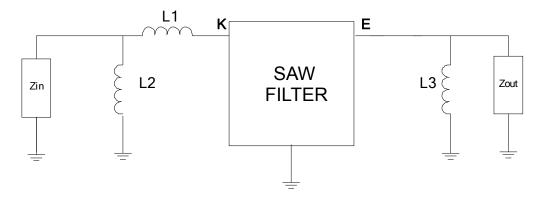
### SF2189A Input Impedance (K Port)



## SF2189A Output Impedance (E Port)

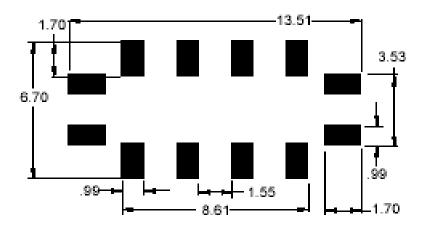


SF2189A 50 ohm Matching Network



L1 = 10 nH, L2 = 27 nH, L3 = 68 nH

SF2189A PCB Pad Layout

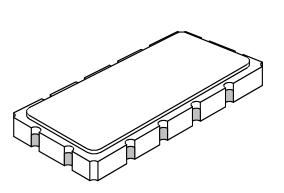


## SM13365-12 Case

## **12-Terminal Ceramic Surface-Mount Case**

#### 13.3 x 6.5 mm Nominal Footprint

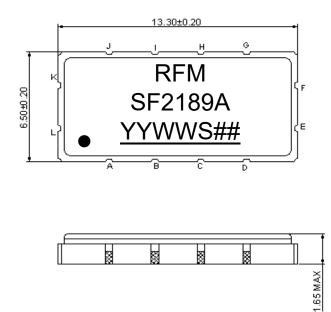
#### Case Dimensions

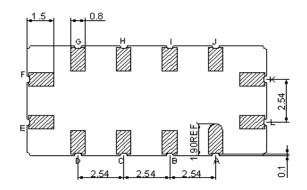


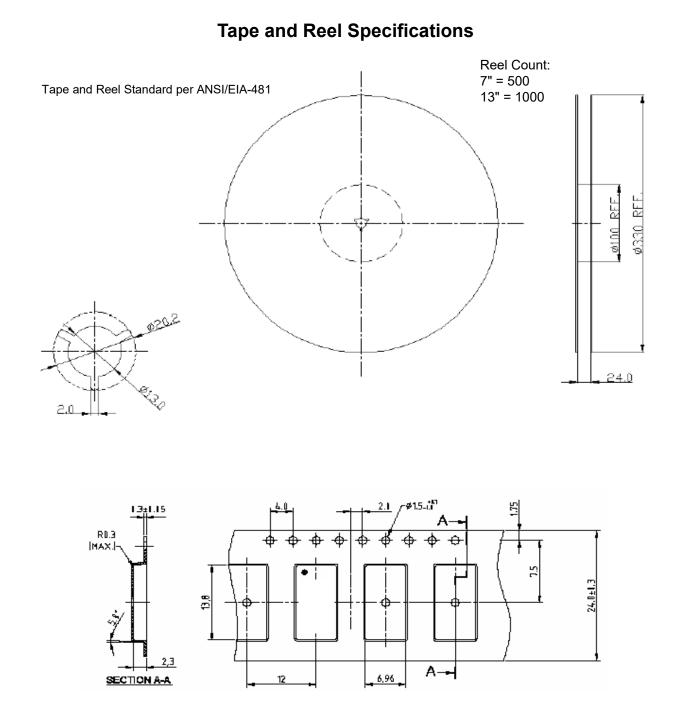
Dimension	mm Inches					
	Min	Nom	Max	Min	Nom	Max
Α	13.08	13.31	13.60	0.515	0.524	0.535
В	6.27	6.50	6.80	0.247	0.256	0.268
С		1.91	2.00		0.075	0.079
D		1.50			0.059	
E		0.79			0.031	
н		1.0			0.039	
Р		2.54			0.100	
Electrical Connections						
Connection			Terminals			

Connection	Terminals
Input	К
Output	E
Case Ground	All others

Materials				
Solder Pad Plating	0.3 to 1.0 µm Gold over 1.27 to 8.89 µm Nickel			
Lid Plating	2.0 to 3.0 µm Nickel			
Body	Al <sub>2</sub> O <sub>3</sub> Ceramic			







#### **Recommended Reflow Profile**

- 1. Preheating shall be fixed at 150~180°C for 60~90 seconds.
- 2. Ascending time to preheating temperature 150°C shall be 30 seconds min.
- 3. Heating shall be fixed at 220°C for 50~80 seconds and at 260°C +0/-5°C peak (10 seconds).
- 4. Time: 5 times maximum.

